

Dual N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^d
30	0.040 at $V_{GS} = 10$ V	5.8
	0.050 at $V_{GS} = 4.5$ V	5.5

Features

- Low Gate Charge
- RoHS Compliant

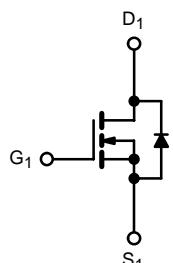
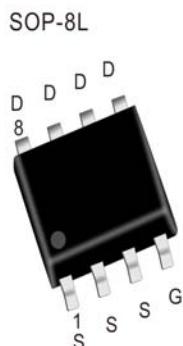
Applications

- Low Current DC/DC Conversion
- Notebook System Power

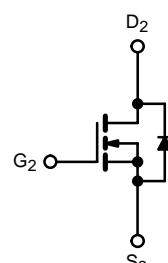
Packing Information

Device	Marking	Reel Size	Tape Width	Quantity
EC4936	13D XXX	12"	13mm	3000pcs

Pin Configuration



N-Channel MOSFET



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Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

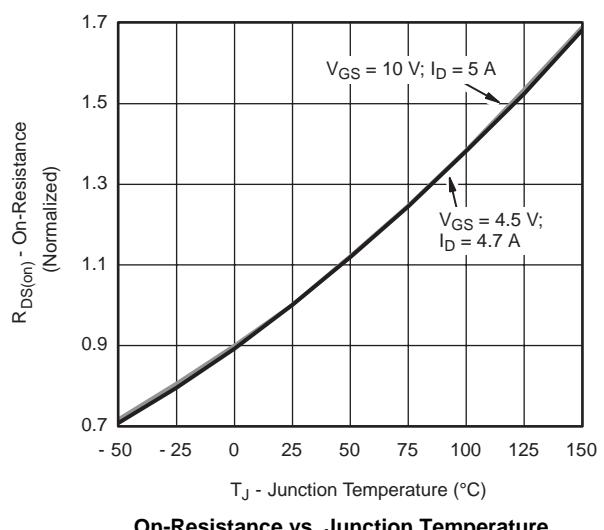
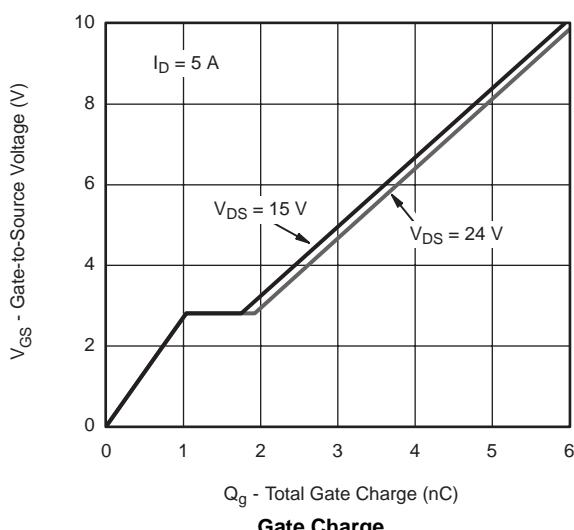
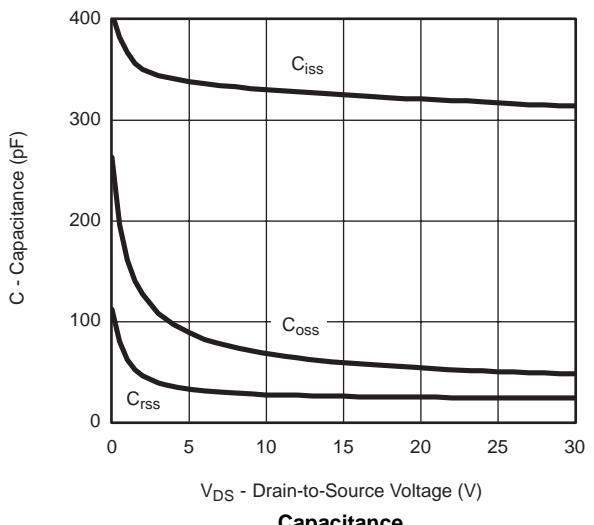
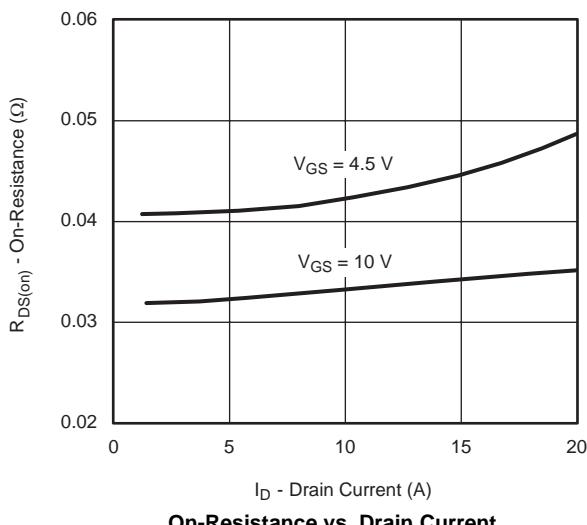
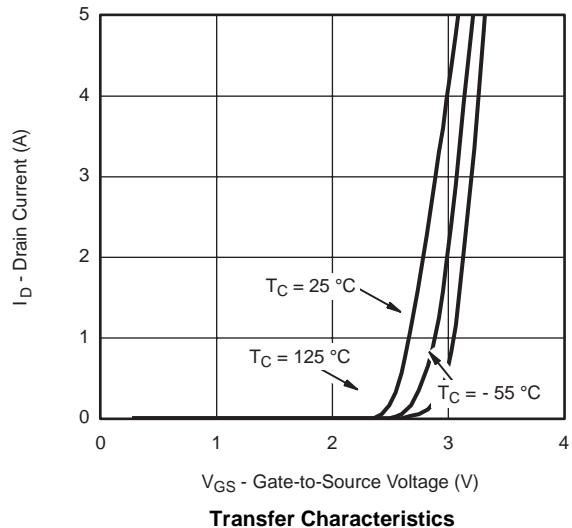
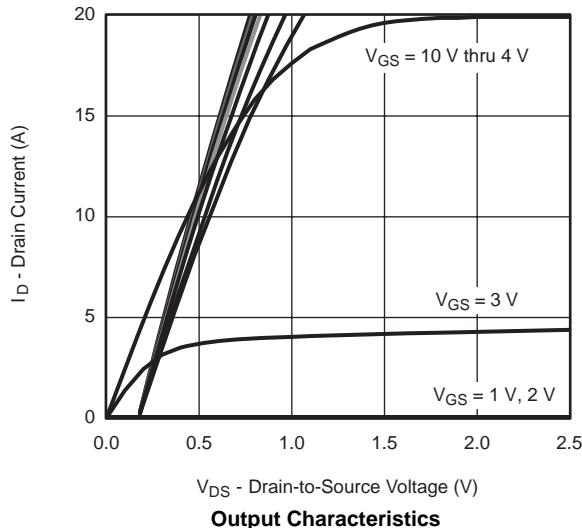
Symbol	Parameter	Value	Unit
P-MOSFET			
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	5.8	A
I_{DM}	Pulse Drain Current	20	A
P_D	Maximum Power Dissipation	2.3	W
T_j	Junction Temperature	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+150	$^\circ\text{C}$
T_L	Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	260	$^\circ\text{C}$
Thermal Resistance Ratings			
R_{thJA}	Maximum Junction-to-Ambient $t \leq 10$ s	75	$^\circ\text{C}/\text{W}$
R_{thJF}	Maximum Junction-to-Foot (Drain) Steady State	55	$^\circ\text{C}/\text{W}$

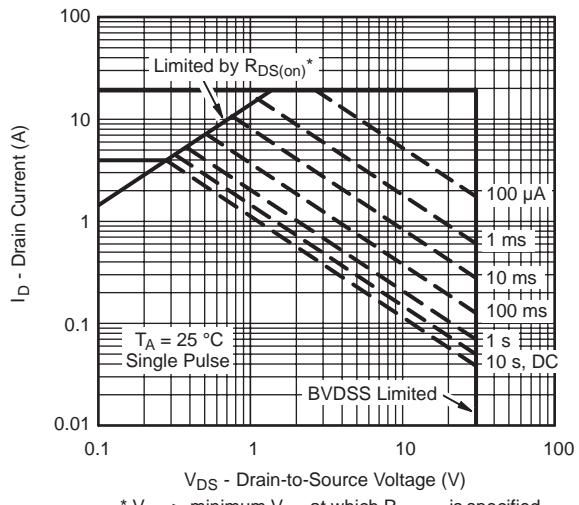
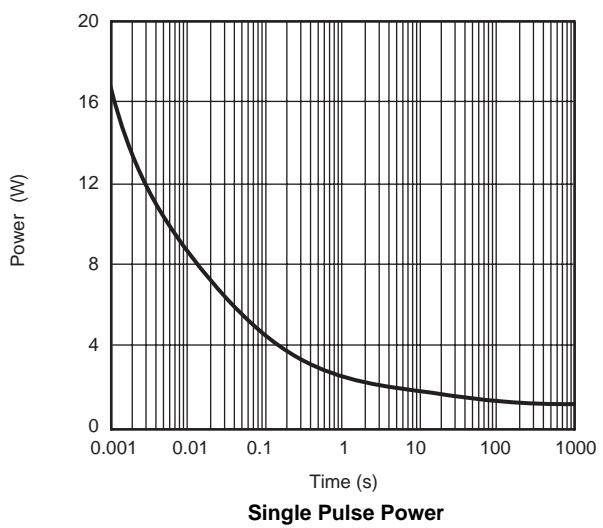
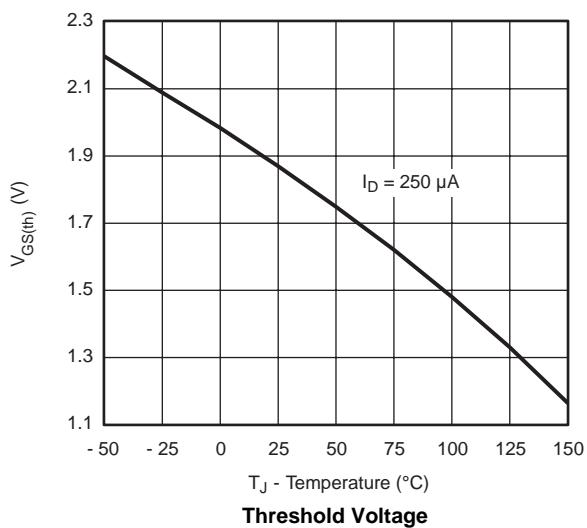
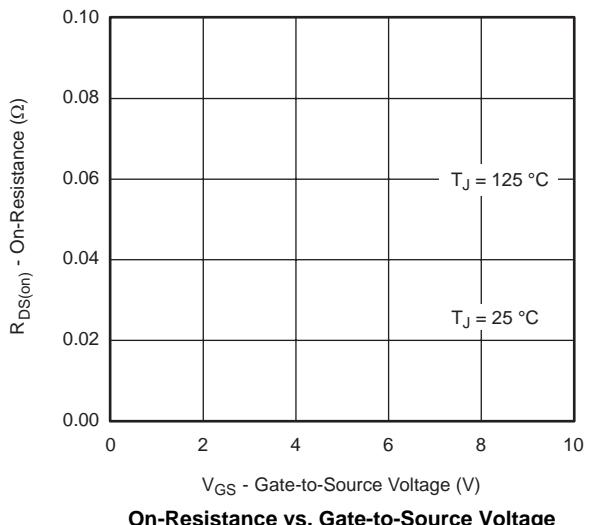
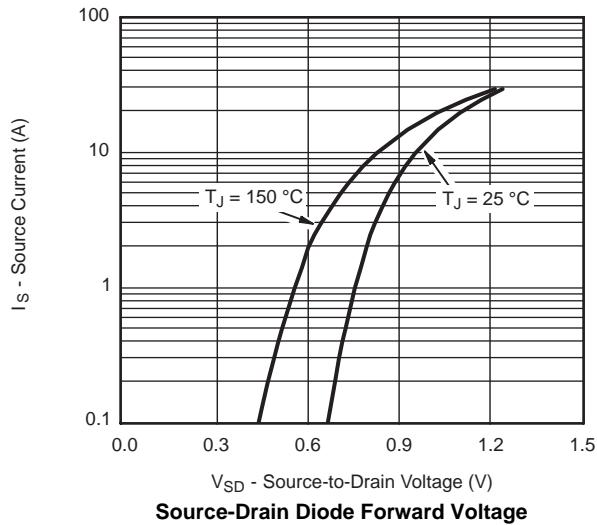
Notes:

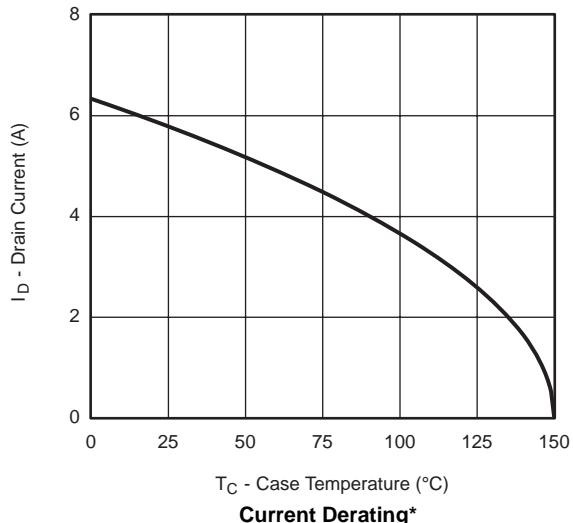
- Surface Mounted on 1" x 1" FR4 board.
- $t = 10$ s.
- Maximum under Steady State conditions is 110 $^\circ\text{C}/\text{W}$.
- Based on $T_C = 25$ $^\circ\text{C}$.

Electrical Characteristics (T_J=25°C Unless Otherwise Specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D = 250 μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-16V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = 250 μA	1.2		3.0	V
Drain-source on-resistance(note1)	R _{DS(on)}	V _{GS} =10V, I _D =-5A		33	40	mΩ
		V _{GS} =4.5V, I _D = 4.7A		41	50	mΩ
Forward transconductance(note1)	g _{FS}	V _{DS} = 10V, I _D = 5A		15		S
Diode forward voltage(note1)	V _{SD}	I _S =A, V ₄ GS = 0V		0.8	1.2	V
DYNAMIC						
Input capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f =1MHz			325	pF
Output capacitance	C _{oss}				60	pF
Reverse transfer capacitance	C _{rss}				30	pF
SWITCHING PARAMETERS (note 2)						
Turn-on delay time	t _{d(on)}	V _{GS} =4.5V, V _{DD} = 15V, R _L =3.8Ω R _G =1Ω, I _D =4 A		12	18	ns
Turn-on rise time	t _r			13	20	ns
Turn-off delay time	t _{d(off)}			16	25	ns
Turn-off fall time	t _f			11	17	ns
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =4.5V, I _D =5A		2.8	4.2	nC
Gate-Source Charge	Q _{gs}			1.1		nC
Gate-Drain Charge	Q _{gd}			0.8		nC

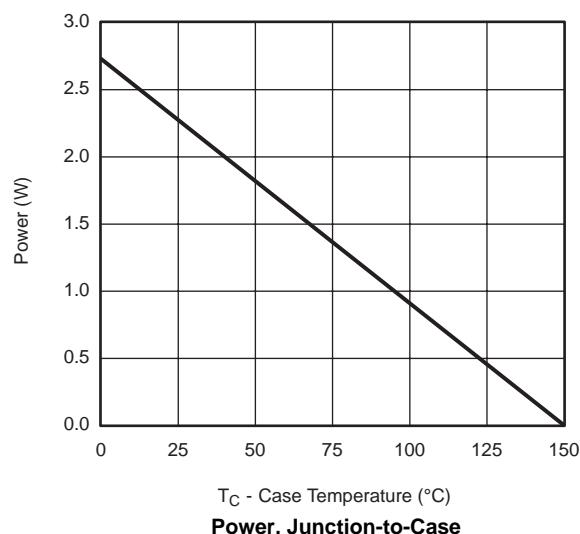
MOSFET TYPICAL CHARACTERISTICS (25°C, unless otherwise noted)


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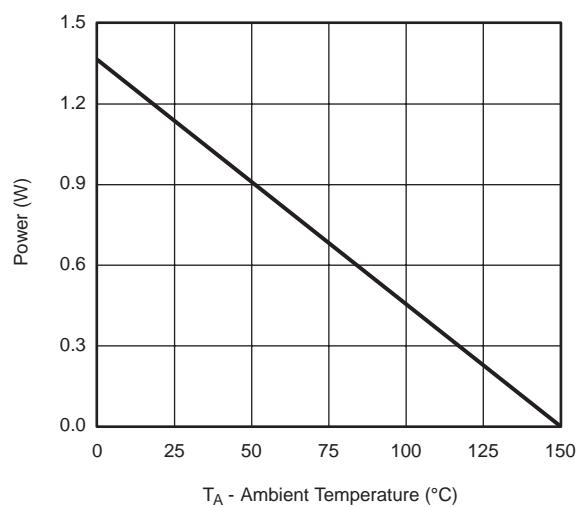
T_C - Case Temperature (°C)

Current Derating*



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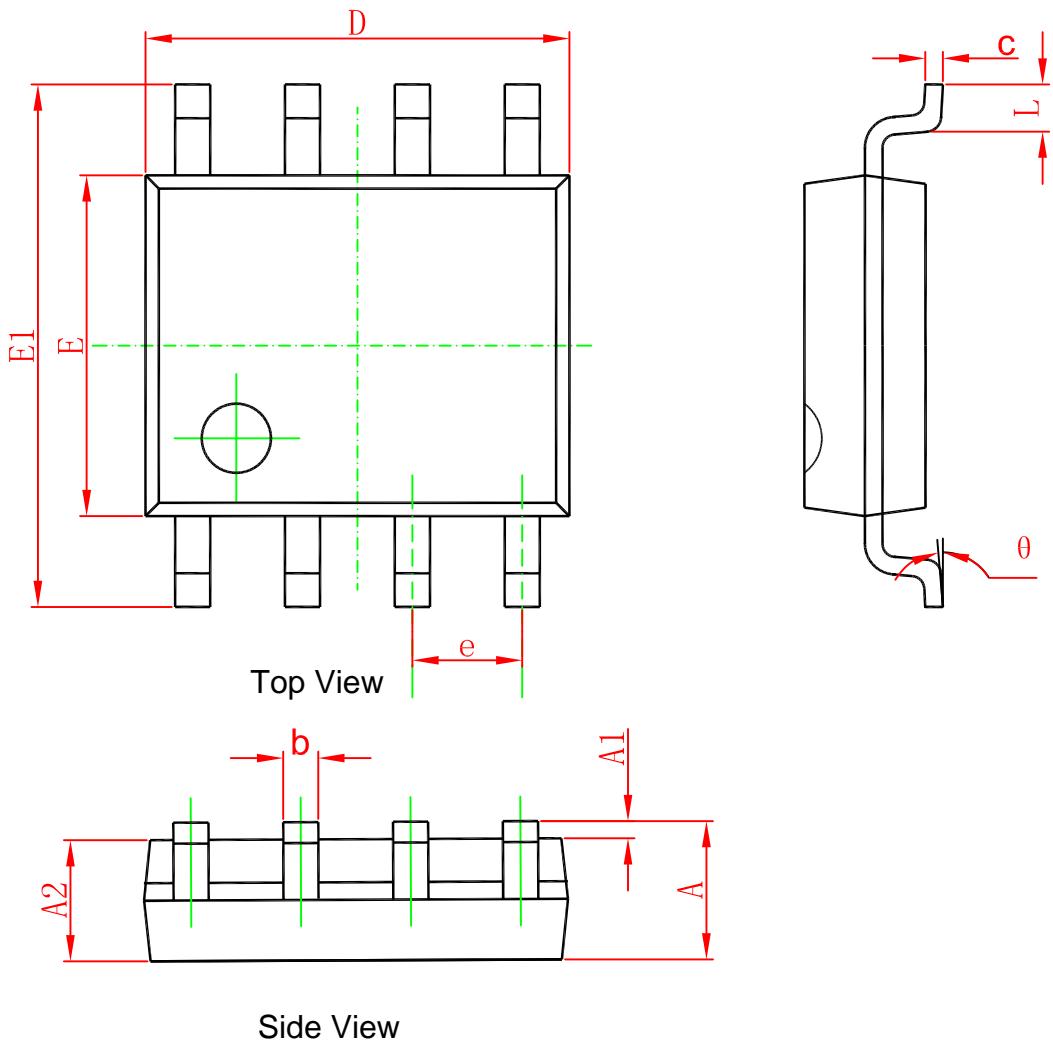
Power, Junction-to-Case



T_A - Ambient Temperature (°C)

Power, Junction-to-Ambient

SOP-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°